# FK350301

### Silicon N-channel MOS FET

#### For switching circuits

#### Overview

FK350301 is N-channel small signal MOS FET employed small size surface mounting package.

#### Features

- Low drain-source ON resistance:  $R_{DS(on)}$  typ. = 2  $\Omega$  ( $V_{GS}$  = 4.0 V)
- High-speed switching
- Small size surface mounting package: SMini3-F2-B
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

#### Packaging

FK3503010L Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

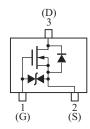
#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Drain-source surrender voltage	V <sub>DSS</sub>	30	V	
Gate-source surrender voltage	V <sub>GSS</sub>	±12	V	
Drain current	ID	100	mA	
Peak drain current	I <sub>DP</sub>	200	mA	
Power dissipation	P <sub>D</sub>	150	mW	
Channel temperature	T <sub>ch</sub>	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

#### Package

- Code
  - SMini3-F2-B Package dimension clicks here.→
- Pin Name
  - 1: Gate
  - 2: Source
  - 3: Drain
- Marking Symbo: X1

#### Internal Connection

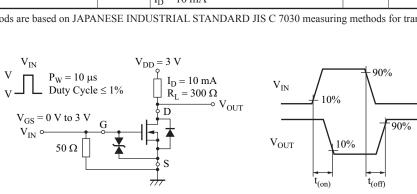


### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

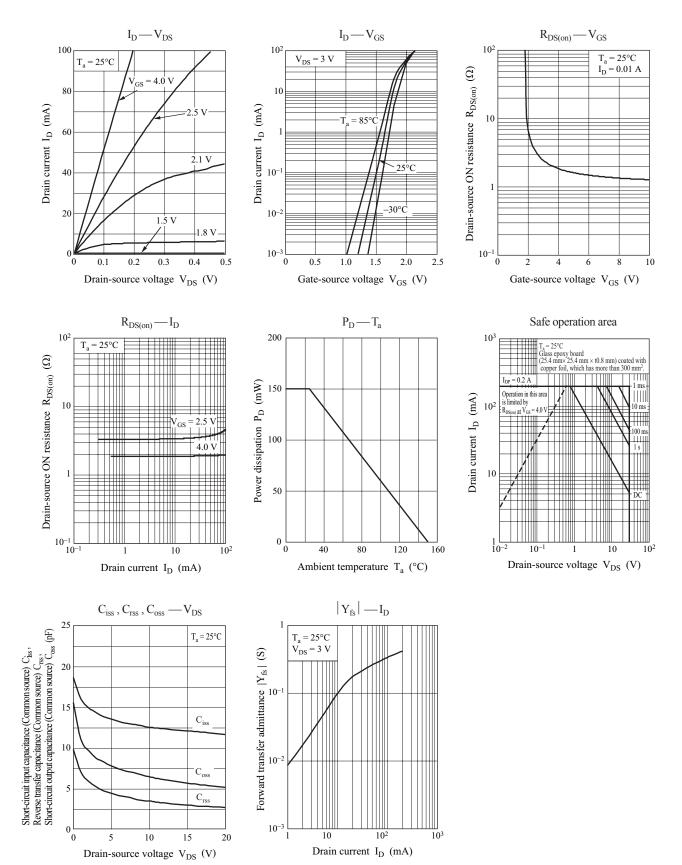
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain-source surrender voltage	V <sub>DSS</sub>	$I_{\rm D} = 1 \text{ mA}, V_{\rm GS} = 0 \text{ V}$	30			V
Drain-source cutoff current	I <sub>DSS</sub>	$V_{\rm DS} = 30$ V, $V_{\rm GS} = 0$ V			1.0	μΑ
Gate-source cutoff current	I <sub>GSS</sub>	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$			±10	μΑ
Gate threshold voltage	V <sub>TH</sub>	$I_D = 1.0 \ \mu A, V_{DS} = 3.0 \ V$	0.5	1.0	1.5	V
Drain-source ON resistance	R <sub>DS(on)</sub>	$I_D = 10 \text{ mA}, V_{GS} = 2.5 \text{ V}$		3	6	Ω
		$I_D = 10 \text{ mA}, V_{GS} = 4.0 \text{ V}$		2	3	Ω
Forward transfer admittance	$ \mathbf{Y}_{\mathrm{fs}} $	$I_D = 10 \text{ mA}, V_{DS} = 3.0 \text{ V}$	20	55		ms
Short-circuit input capacitance (Common source)	C <sub>iss</sub>	$V_{DS} = 3 V, V_{GS} = 0 V, f = 1 MHz$		12		pF
Short-circuit output capacitance (Common source)	C <sub>oss</sub>			7		pF
Reverse transfer capacitance (Common source)	C <sub>rss</sub>			3		pF
Turn-on time *	t <sub>on</sub>	$V_{DD} = 3 V, V_{GS} = 0 V \text{ to } 3 V,$ $I_{D} = 10 \text{ mA}$		100		ns
Turn-off time *	t <sub>off</sub>	$V_{DD} = 3 \text{ V}, V_{GS} = 3 \text{ V} \text{ to } 0 \text{ V},$ $I_D = 10 \text{ mA}$		100		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors. 2. \*: Test circuit





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